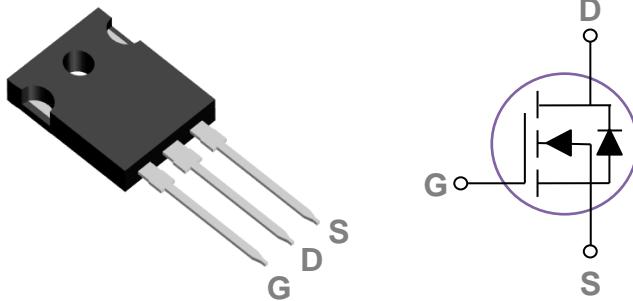


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

TO247 Pin Configuration



BVDSS	RDS(ON)	ID
100V	4.5mΩ	160A

Features

- 100V, 160A, RDS(ON) = 4.5mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- Networking
- Load Switch
- LED applications
- Quick Charger

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
V _{Gs}	Gate-Source Voltage	±20	V
I _D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	160	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	102	A
I _{DM}	Drain Current – Pulsed ¹	640	A
EAS	Single Pulse Avalanche Energy ²	405	mJ
I _{AS}	Single Pulse Avalanche Current ²	90	A
P _D	Power Dissipation ($T_c=25^\circ\text{C}$)	305	W
	Power Dissipation – Derate above 25°C	2.44	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	0.41	°C/W



100V N-Channel MOSFETs

PDX09D8BH

Electrical Characteristics (T_J=25 °C, unless otherwise noted)**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =25°C	---	---	1	uA
		V _{DS} =80V , V _{GS} =0V , T _J =85°C	---	---	10	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance ³	V _{GS} =10V , I _D =20A	---	3.7	4.5	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	2	2.6	4	V
g _{fS}	Forward Transconductance	V _{DS} =10V , I _D =3A	---	17	---	S

Dynamic and switching Characteristics

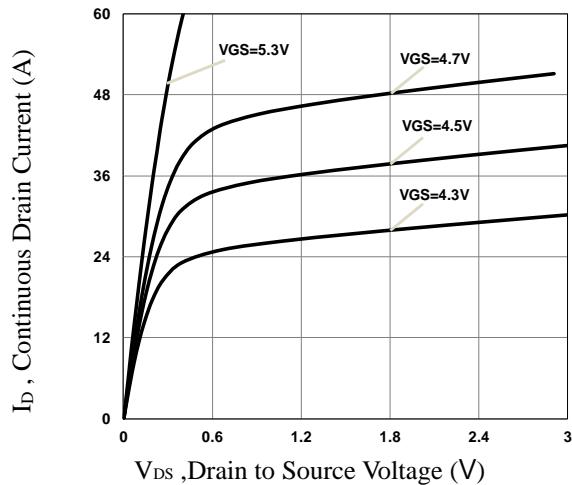
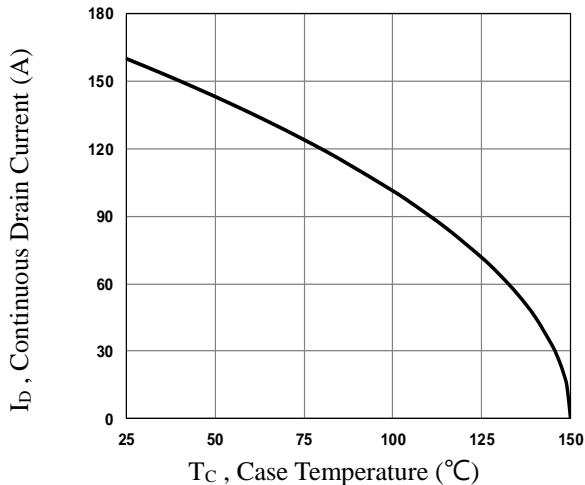
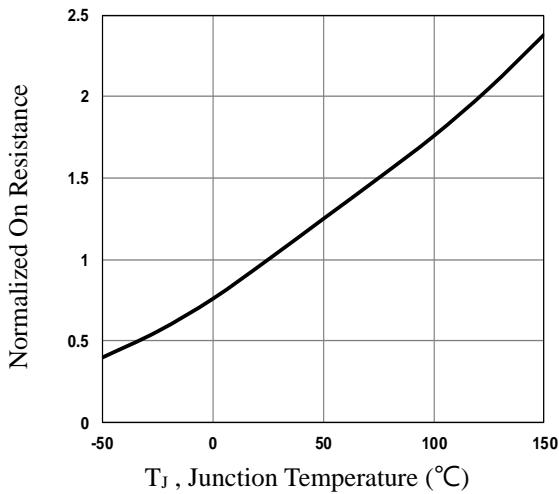
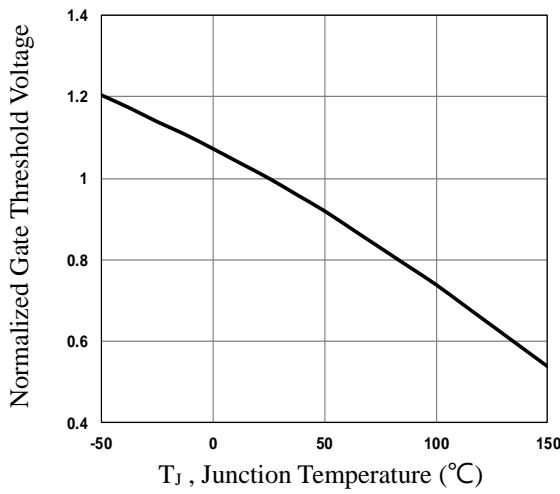
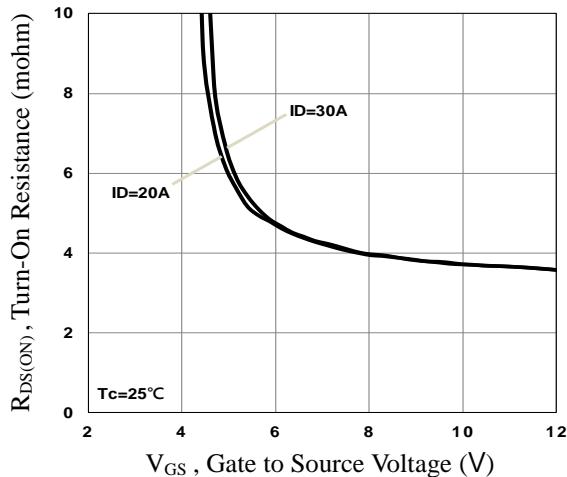
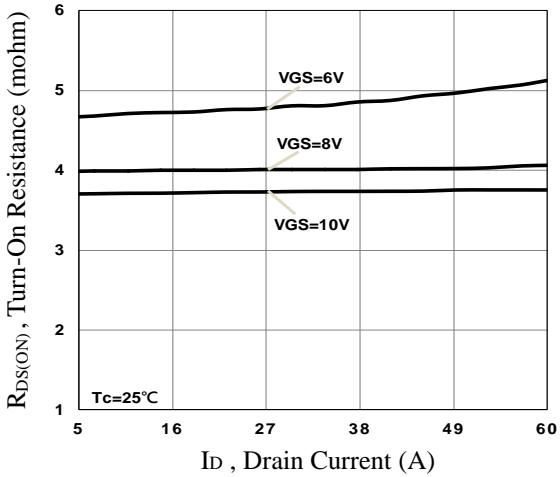
Q _g	Total Gate Charge ^{3, 4}	V _{DS} =50V , V _{GS} =10V , I _D =80A	---	56	85	nC
Q _{gs}	Gate-Source Charge ^{3, 4}		---	13.5	20	
Q _{gd}	Gate-Drain Charge ^{3, 4}		---	15	25	
T _{d(on)}	Turn-On Delay Time ^{3, 4}	V _{DD} =50V , V _{GS} =10V , R _G =6Ω I _D =80A	---	24	36	ns
T _r	Rise Time ^{3, 4}		---	20	30	
T _{d(off)}	Turn-Off Delay Time ^{3, 4}		---	45	70	
T _f	Fall Time ^{3, 4}		---	25	40	
C _{iss}	Input Capacitance	V _{DS} =50V , V _{GS} =0V , F=1MHz	---	3750	5650	pF
C _{oss}	Output Capacitance		---	750	1150	
C _{rss}	Reverse Transfer Capacitance		---	10	15	
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	---	1.8	---	Ω

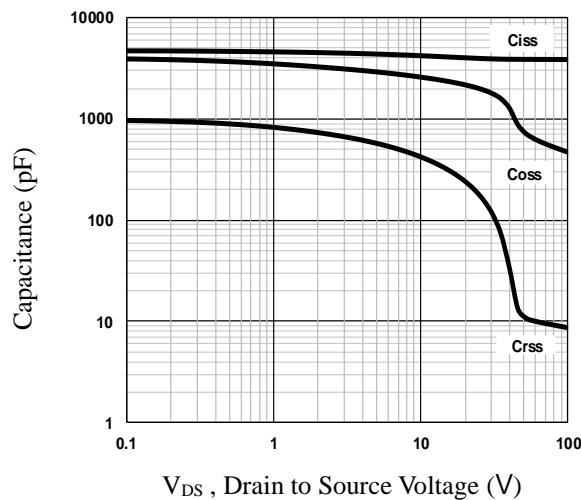
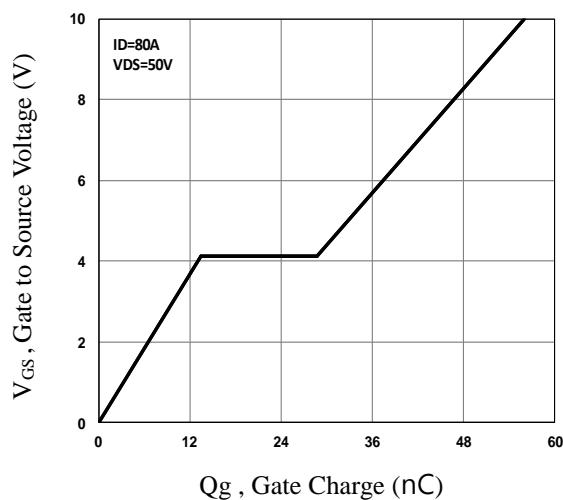
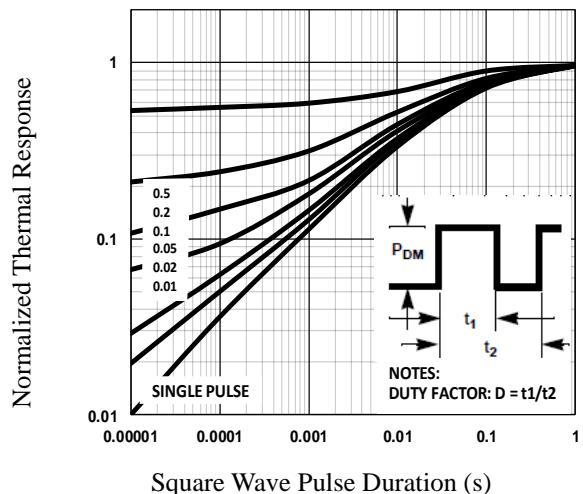
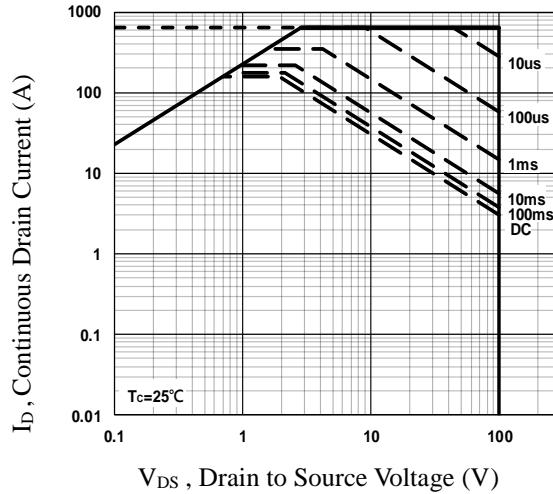
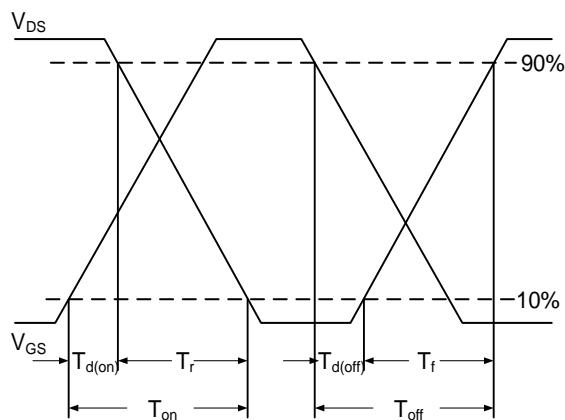
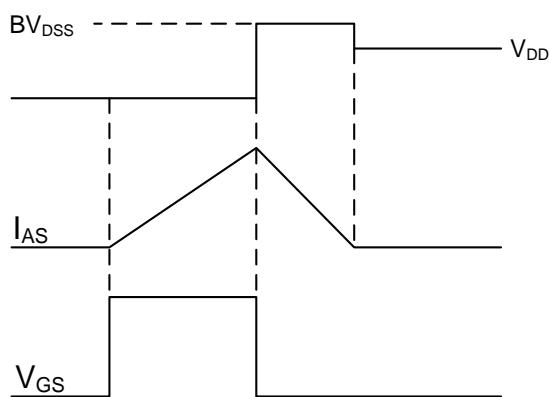
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _s	Continuous Source Current	V _G =V _D =0V , Force Current	---	---	160	A
I _{SM}	Pulsed Source Current		---	---	320	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _s =1A , T _J =25°C	---	---	1	V
t _{rr}	Reverse Recovery Time	V _R =100V, I _s =10A di/dt=100A/μs , T _J =25°C	---	210	---	ns
Q _{rr}	Reverse Recovery Charge		---	510	---	nC

Note :

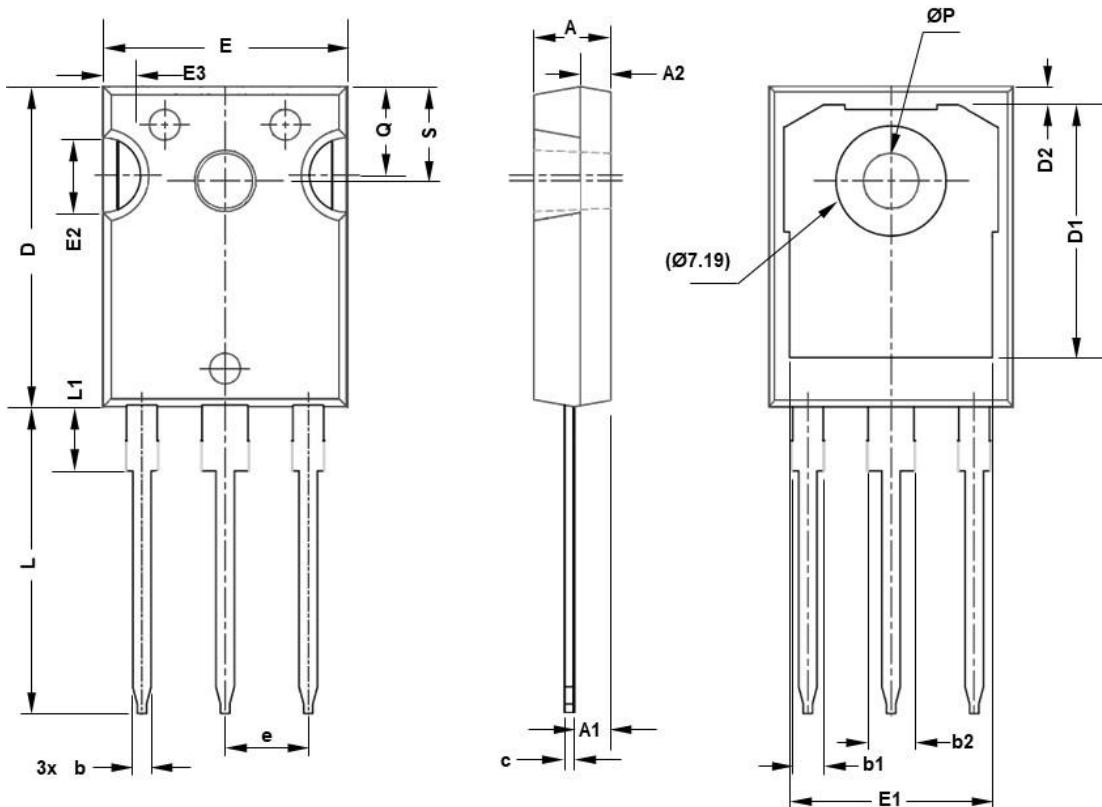
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=50V, V_{GS}=10V,L=0.1mH,I_{AS}=90A.,R_G=25Ω,Starting T_J=25°C.
3. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
4. Essentially independent of operating temperature.


Fig.1 Typical Output Characteristics

Fig.2 Continuous Drain Current vs. T_c

Fig.3 Normalized $R_{DS(ON)}$ vs. T_J

Fig.4 Normalized V_{th} vs. T_J

Fig.5 Turn-On Resistance vs. V_{GS}

Fig.6 Turn-On Resistance vs. I_D

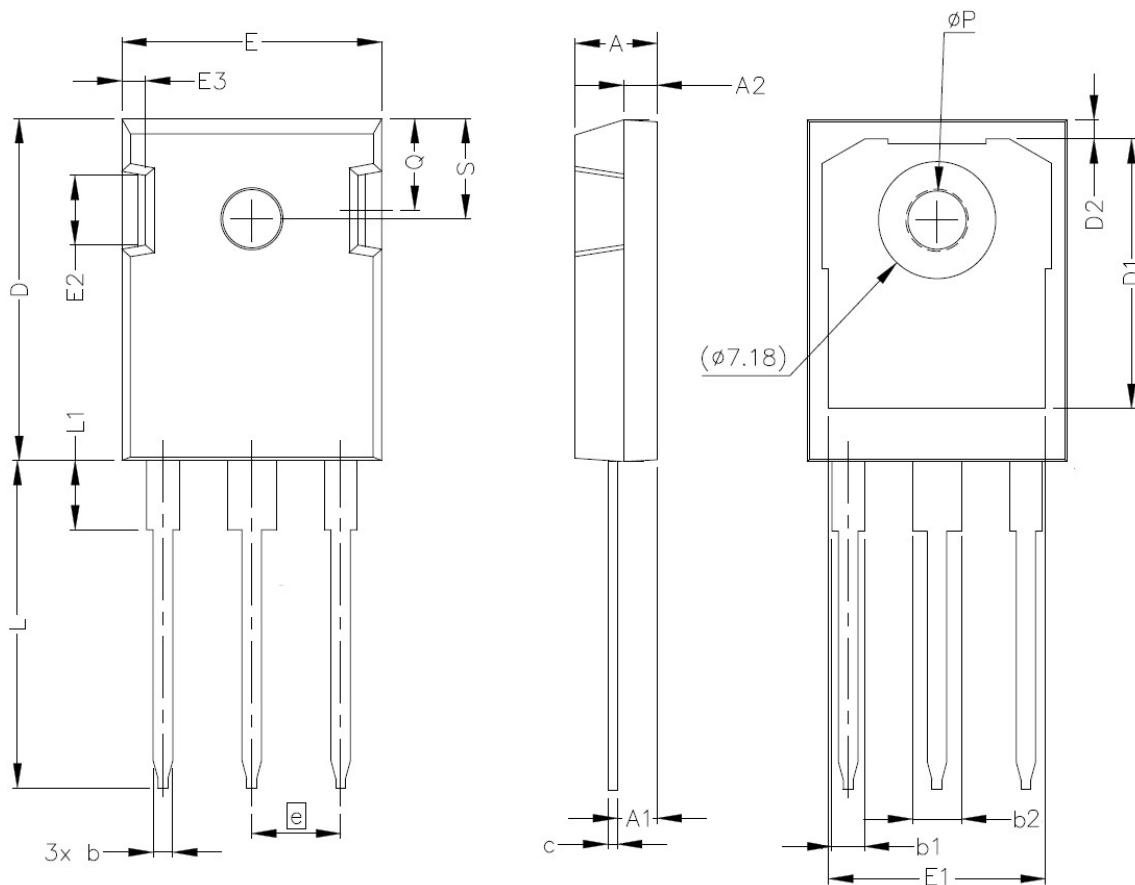

Fig.7 Capacitance Characteristics

Fig.8 Gate Charge Characteristics

Fig.9 Normalized Transient Impedance

Fig.10 Maximum Safe Operation Area

Fig.11 Switching Time Waveform

Fig.12 EAS Waveform

TO247 PACKAGE INFORMATION

VERSION A



SYMBOL	mm		SYMBOL	mm	
	MIN	MAX		MIN	MAX
A	4.83	5.21	E2	4.32	5.49
A1	2.29	2.55	E3	2.15	2.80
A2	1.50	2.49	e	5.44BSC	
b	1.12	1.33	L	19.81	20.32
b1	1.91	2.39	L1	4.10	4.40
b2	2.87	3.22	ΦP	3.56	3.65
C	0.55	0.69	Q	5.39	6.20
D	20.80	21.10	S	6.04	6.30
D1	16.25	17.65			
D2	0.51	1.35			
E	15.75	16.13			
E1	13.46	14.16			

VERSION B


SYMBOL	mm		SYMBOL	mm	
	MIN	MAX		MIN	MAX
A	4.75	5.25	E2	3.70	5.30
A1	2.16	2.66	E3	1.00	2.75
A2	1.75	2.25	e	5.44BSC	
b	1.07	1.35	L	19.52	20.32
b1	1.90	2.41	L1	4.10	4.40
b2	2.87	3.38	ΦP	3.35	3.85
C	0.50	0.70	Q	5.40	6.20
D	20.60	21.40	S	6.15BSC	
D1	16.15	17.65			
D2	0.95	1.35			
E	15.50	16.10			
E1	12.40	13.60			